

DOCKET NO: 251598US0



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
YUKIO HOSAKA, ET AL. : EXAMINER: RACHUBA, MAURINA T.
SERIAL NO: 10/820,123 :
FILED: APRIL 8, 2004 : GROUP ART UNIT: 3723
FOR: ABRASIVE PAD, METHOD AND :
METAL MOLD FOR MANUFACTURING :
THE SAME, AND SEMICONDUCTOR :
WAFER POLISHING METHOD :

AMENDMENT AND REQUEST FOR RECONSIDERATION

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

In response to the Official Action dated April 12, 2007, reconsideration is respectfully requested in the above-identified application in view of the following amendments and remarks:

Amendments to the Claims begin on page 2 of this response.

Support for the Amendments begin on page 7 of this response.

Remarks begin on page 8 of this response.

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DO NOT ENTER: /M.R./